KCASI Cleanroom Rates - Effective for FY26 (July1, 2025 - June 30, 2026)

Item Description	**Details**	**Internal (OUS) rate**	**External academic, non-profit, govt.**	**Internship****	**Industry rate**	**Daily / Hourly**
Houry rate	Hourly rate covers entry to clean room, gowning, and access to basic priocess tools including benches, spinners, microscope and filmetrics.	35	50	72.5	110	Hourly. Min charge $10.
Engineering time	Training, maintence, and service fee for Engineer assistance	90	112.5	112.5	112.5	Hourly
User training and set-up	Issue gown, gowning and safety training, Nemo registration, notebook	125	150	150	200	per user
Cap and Notch Values	Monthly fee cap value and notch value. Usage above notch is 30% of regular fees	$2100/mo; $4000 notch; 30% after notch	$2100/mo; $4000 notch; 30% after notch	$4500/mo; $7500 notch; 30% after notch	$7000/mo; $11000 notch; 30% after notch	NA
NOTE: Tool Rates: All hourly use items will have a $5 min fee, or 15 minute minimum useage fee- which ever is greater.						
Keyence VHX 7000	High res with plenty of advanced features. Not located in cleanroom - does not require hourly lab access fee to use	30	45	60	90	hourly
Filmetrics F40	Standard thin film measurement	included	included	included	included	hourly
Flexus FLX 2320	Thin Film stress measurement	5	5	10	15	hourly
Olympus Inspection Microscope	Inspection microscope	included	included	included	included	included
KLA Profilometer	Stylus profilometer	20	20	30	40	Hourly
PlasmaTherm DSE-III	Deep Si etch system (flourine based)	30	30	57.5	85	Hourly
PlasmaTherm PECVD	Primary plasma deposition system (**Specialty gases my require additional consumable fees.**)	40	40	62.5	85	Hourly
PlasmaThrerm Corial RIE	Primary plasma etch system (flourine based)	30	30	57.5	85	Hourly
AJA E-beam Evaporator	Metal evaporator. Basic metals will be provided. **Precious metals to be purcahsed from the Cleanroom.**	30	30	57.5	85	Hourly
AJA Sputterer	Basic targets will be provided. **Users required to purchase AJA custom targets from Cleanroom.**	30	30	57.5	85	Hourly
ADT Dicing Saw	Primary wafer dicing saw	30	30	47.5	65	Hourly
Heidelberg Direct Laser Writer	MLA 150 - Foundation for photolithography	40	40	62.5	85	Hourly
YES HMDS priming oven	For substrate priming	10	10	20	30	Hourly
Anatech Asher	For substrate sufrace conditioning/PR stripping	15	15	30	45	Hourly
SUSS MA6/BA6 aligner	Primary UV aligner/exporure tool	30	30	52.5	75	Hourly
Photoresist bench (includes spinners)	For PR dispensing and spinning	included	included	included	included	included
Solvent bench	For Solvent processing	included	included	included	included	included
Acid bench	For Acid processing	included	included	included	included	included
Developer bench	For Acid processing	included	included	included	included	included

*** All visitors, tours, workshop, and instructional guest users require approval to enter from the Cleanroom Engineer.**